Hybrid 8j371 Traveler

June 9, 2000

1 Connectivity

Repairs on shorts:
Fixes for opens:

2 Chips

The following chips were assembled on this hybrid (in the order that the chips get read out):
Hybrid 8J371 has die: 169-023 169-024 169-025 169-026 245-034 245-035 245-036 245-044

3 Data Analysis Summary

The following summarizes the findings of the Burn-in data analysis program. The first chip in the readout name is numbered 0.

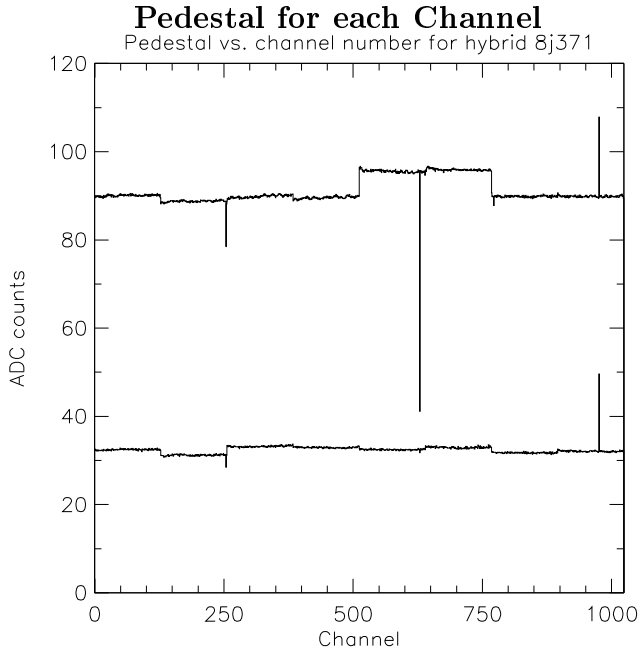
```
% Hybrid 8j371 classification info. Created 09:26:17 06/09/00

Hybrid 8j371 quality: fair
Chip classification: fair fair good good fair good fair fair
Bad channels (chip-channel): 1-126 4-15 4-117 6-4 7-80
Bad cells: none
Random bad capacitors (chip-cell-channel): 0-17-8 0-33-9 0-35-47
   0-39-29 0-44-105 1-10-125 1-10-127 1-37-14
Channels at pedestal needed for DCMS: 32.6 31.6 30.7 31.6 29.8 31.6 31.6 31.6
```

4 Comments

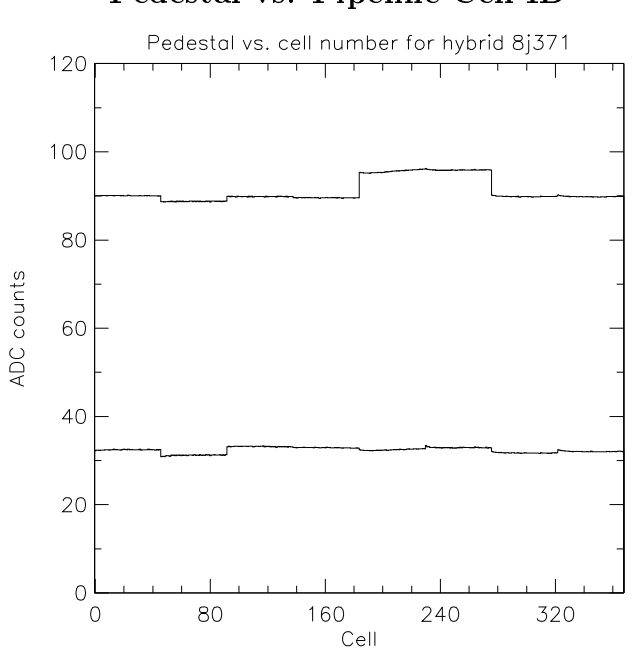
HV tested.

5 Pedestal

The following plot shows the pedestals vs. channel number with and without charge injection:



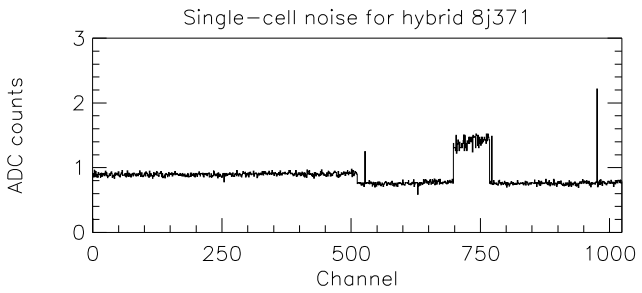
The following plot shows the average pedestal vs. pipeline cell ID with and without charge injection. The x-axis is cell ID offset by 46 for each chip. Thus cell ID 5 for chip 1 is at x=5, chip 2 at x=51, chip 3 at x=97, etc.

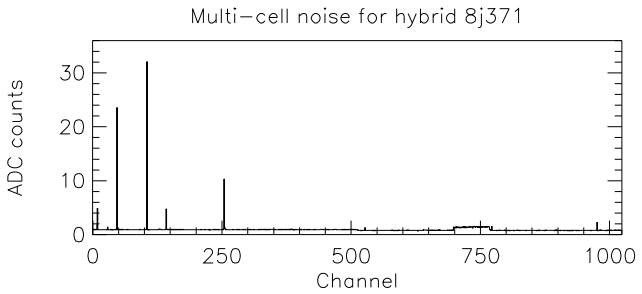


6 Noise

The following plots show the single-cell and multi-cell RMS noise:

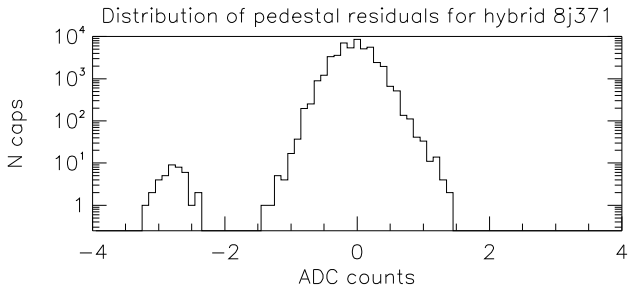
RMS Noise

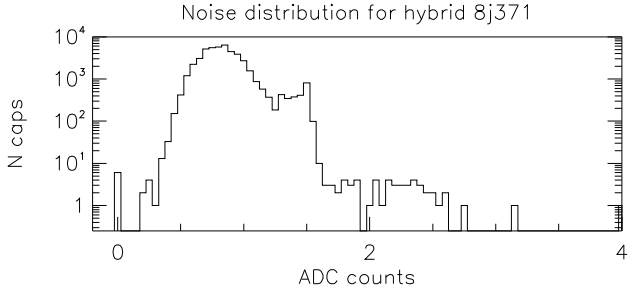




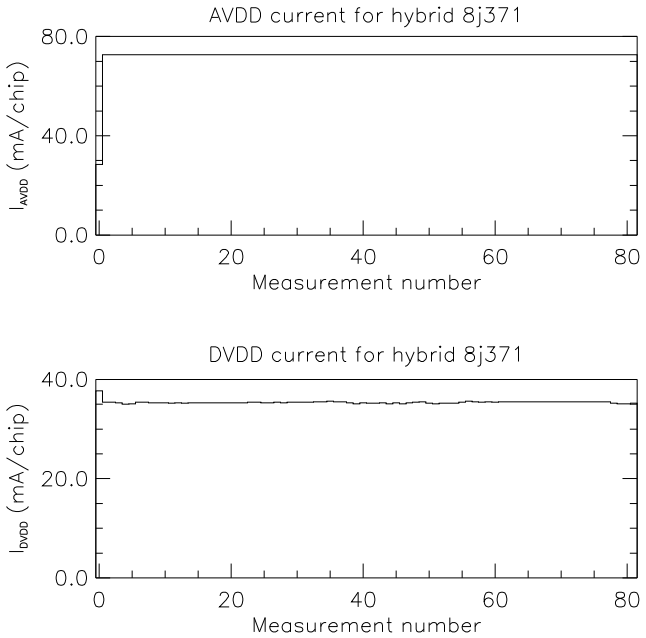
The following are histograms of the pedestal of each pipeline capacitor relative to the chip average (top); and the RMS noise of each capacitor (bottom):

Distribution of Pedestals and Noise





7 Currents

The following plots show the supply currents per chip as a function of measurment number. Currents are measured approximately every 10 minutes:

Supply Currents During Burn-in